

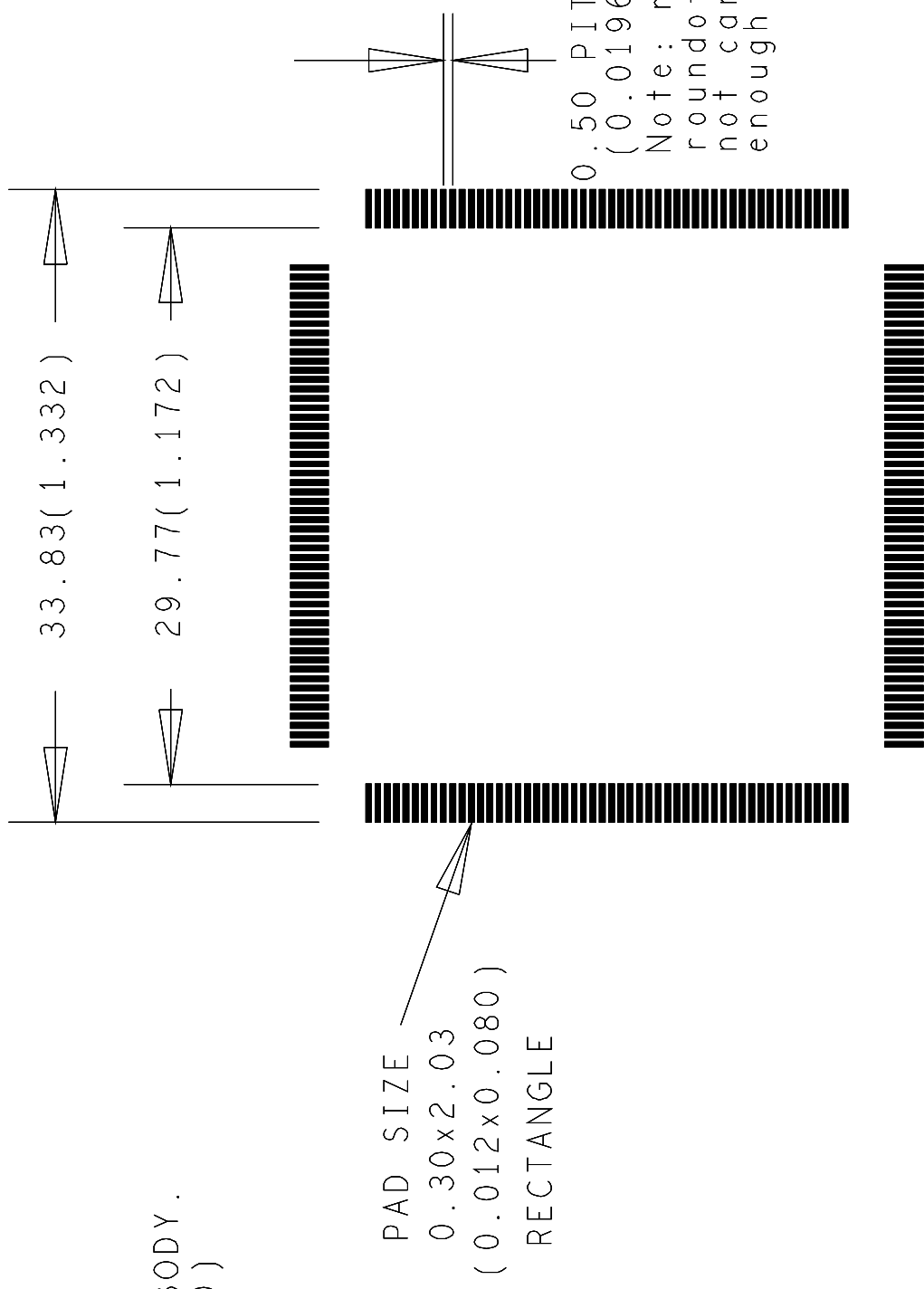
DIMENSIONS: mm(inches)

LEAD FORMING GUIDELINES:

APPLY THE FOLLOWING LEAD FORMING GUIDELINES TO ENSURE THE 208-LEAD CERAMIC QFP WILL FIT ONTO THIS FOOTPRINT.

- 1) FIRST LEAD BEND IS $1.14 \pm .13$ ($.045 \pm .005$) FROM THE BODY.
- 2) SECOND LEAD BEND IS MADE $2.67 -0/+ .51$ ($.105 -0/+ .020$) TO ALLOW PWB TO COMPONENT BODY CLEARANCE.
- 3) THE HEAL OF THE FOOT IS OFFSET FROM THE FIRST BEND BY $0-.46$ ($0-.018$).
- 4) THE FOOT OF THE LEAD IS $1.14 \pm .13$ ($.045 \pm .005$).

THESE LEAD FORMING GUIDELINES ARE COMPATABLE WITH IPC/EIA J-STD-001C FOR NOMINAL SOLDER FILLETS AND IPC-SM-782 FOR LAND PATTERN DESIGN.



RECOMMENDED FOOTPRINT FOR AEROFLEX
208-PIN CERAMIC QUAD FLAT PACKAGE (CQFP)